ABSTRACT

INTEGRATED CIRCUIT HARD MASK PROCESSING SYSTEM

An integrated circuit hard mask processing system is provided including providing a substrate having an integrated circuit; forming an interconnect layer over the integrated circuit; applying a low-K dielectric layer over the interconnect layer; applying a hard mask layer over the low-K dielectric layer; forming a via opening through the hard mask layer and the low-K dielectric layer to the interconnect layer; applying a first fluid and a second fluid in the via opening for removing an overhang of the hard mask layer; depositing an interconnect metal in the via opening; and chemical-mechanical polishing the interconnect metal and the ultra low-K dielectric layer.

Fig. 1